

PCN Number:	20180521000	PCN Date:	May 31, 2018
Title:	Datasheet for LMK03328		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMK03328

SNAS668D –AUGUST 2015–REVISED APRIL 2018

Changes from Revision C (December 2017) to Revision D

Page

- Clarified note about V_{OH} (rail-to-rail swing only with $V_{DDO} = 1.8\text{ V} \pm 5\%$)..... 12
- Changed Slew Rate minimum and maximum from: 2.25 V/ns and 5 V/ns to: 1 V/ns and 4 V/ns, respectively 15
- Updated REVID to be 0x02 (was 0x01) 78
- Added the *Support for PCB Temperature up to 105°C* subsection..... 146



LMK03318

SNAS669E –SEPTEMBER 2015–REVISED APRIL 2018

Changes from Revision D (December 2017) to Revision E

Page

- Clarified note about V_{OH} (rail-to-rail swing only with $V_{DDO} = 1.8\text{ V} \pm 5\%$)..... 12
- Changed Slew Rate minimum and maximum from: 2.25 V/ns and 5 V/ns to: 1 V/ns and 4 V/ns, respectively 14
- Updated PRODID reset value to be 0x33 (was 0x31)..... 71
- Updated REVID reset value to be 0x02 (was 0x01) 71
- Added the *Support for PCB Temperature up to 105°C* subsection..... 133

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMK03328	SNAS668C	SNAS668D
LMK03318	SNAS669D	SNAS669E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMK03328>

<http://www.ti.com/product/LMK03318>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMK03328RHSR	LMK03328RHST	LMK03318RHSR	LMK03318RHST
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com